g	GE	Energy	Functional Testing Specification
	Parts & Repair Services Louisville, KY		LOU-GED-DS200TBCB

Test Procedure for a RTD 4/20ma Input 0-1ma option terminal board

DOCUI	DOCUMENT REVISION STATUS: Determined by the last entry in the "REV" and "DATE" column			
REV.	DESCRIPTION	SIGNATURE	REV. DATE	
Α	Initial release	J. Wychulis	7/23/2009	
В	Added section 6.3, burning in the card	G. Chandler	12/12/2013	
С				

© COPYRIGHT GENERAL ELECTRIC COMPANY

Hard copies are uncontrolled and are for reference only.

PROPRIETARY INFORMATION – THIS DOCUMENT CONTAINS PROPRIETARY INFORMATION OF GENERAL ELECTRIC COMPANY AND MAY NOT BE USED OR DISCLOSED TO OTHERS, EXCEPT WITH THE WRITTEN PERMISSION OF GENERAL ELECTRIC COMPANY.

PREPARED BY J. Wychulis	REVIEWED BY G. Chandler	REVIEWED BY	QUALITY APPROVAL Charlie Wade
DATE	DATE 42/42/2012	DATE	DATE 7/20/2000
23 July 09	12/12/2013		7/30/2009

g	5	
LOU-GED-DS200TBCB REV. B	GE Energy Parts & Repair Services Louisville, KY	Page 2 of 3

1. SCOPE

1.1 This is a functional testing procedure for a terminal board.

2. STANDARDS OF QUALITY

2.1 Refer to the current revision of the IPC-A-610 standard for workmanship standards.

3. APPLICABLE DOCUMENTS

- **3.1** The following document(s) shall form part of this specification to the extent specified herein. Unless otherwise indicated, the latest issue shall apply.
 - **3.1.1** See the board's electronic folder for more information

4. **ENGINEERING REQUIREMENTS**

- 4.1 Equipment Cleaning
 - **4.1.1** Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to the local documented procedures for cleaning guidelines.
- **4.2** Equipment Inspection
 - **4.2.1** Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:
 - 4.2.1.1 Wires broken, cracked, or loosely connected
 - 4.2.1.2 Terminal strips / connectors broken or cracked
 - 4.2.1.3 Components visually damaged
 - 4.2.1.4 Capacitors bloated or leaking
 - 4.2.1.5 Solder joints damaged or cold
 - 4.2.1.6 Circuit board burned or de-laminated
 - 4.2.1.7 Printed wire runs / Traces burned or damaged

5. EQUIPMENT REQUIRED

5.1 The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

Qty	Reference #	Description	
1		Fluke 87 DMM (or Equivalent)	
1		Power supply	

	g	
LOU-GED-DS200TBCB	GE Energy	Page 3 of 3
REV. B	Parts & Repair Services	
	Louisville, KY	

6. TESTING PROCESS

6.1 Setup

6.1.1 Put 24VDC across C1 using proper polarity

6.2 Testing Procedure

- **6.2.1** Turn power on.
- **6.2.2** Check the following points on the green terminal connector for 24VDC, +-0.25VDC.
- **6.2.3** 3, 4, 9, 10, 15, 16, 21, 22, 27, 28, 33, 34, 39, 40, 45, 46, 51, 52, 57, 58, 63, 64.
- **6.2.4** Look at schematics and do point to point continuity check on the rest of the connections

6.3 Burning in card

- **6.3.1** Connect +27vdc to JHH-50 with common to JHH-47.
- **6.3.2** Connect a 470 ohm, 2w resistor from common to the following points.
- **6.3.3** TB1-3, TB1-9, TB1-15, TB1-21, TB1-27, TB1-33, TB1-39, TB1-45, TB1-51, TB1-57 and TB1-63.
- **6.3.4** Verify +24vdc +/- 1vdc at each of the TB1 connections
- **6.3.5** Normal repairs; burn card in for 1 hours and verify +24vdc +/- 1vdc at each of the TB1 connections.
- 6.3.6 All Revitalization Cards shall be burned-in for three (3) hours, check text box in SAP to determine if they fall into this category.

6.4 TEST COMPLETE ***

7. Attachments

7.1 None at this time.

8. Notes

8.1 None at this time.